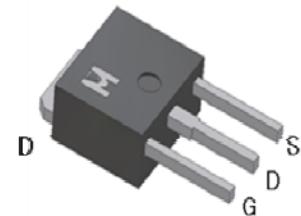
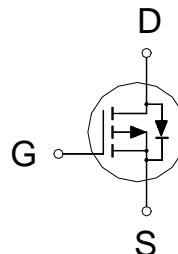


P-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV _{DSS}	-30V
R _{DSON} (MAX.)	6.8mΩ
I _D	-80A



UIS, R_G 100% Tested

Pb-Free Lead Plating & Halogen Free



ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V _{GS}	±25	V
Continuous Drain Current	T _C = 25 °C	I _D	-80	A
	T _C = 100 °C		-51	
Pulsed Drain Current ¹		I _{DM}	-240	
Avalanche Current		I _{AS}	-35	
Avalanche Energy	L = 0.1mH, I _D =-35A, R _G =25 Ω	E _{AS}	61.25	mJ
Power Dissipation	T _C = 25 °C	P _D	78	W
	T _C = 100 °C		31	
Operating Junction & Storage Temperature Range		T _J , T _{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	R _{θJC}		1.6	°C / W
Junction-to-Ambient ³	R _{θJA}		62.5	

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = -250\mu\text{A}$	-30			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1	-1.5	-2	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -24V, V_{GS} = 0V$			-1	μA
		$V_{DS} = -20V, V_{GS} = 0V, T_J = 125^\circ\text{C}$			-10	
On-State Drain Current ¹	$I_{D(\text{ON})}$	$V_{DS} = -5V, V_{GS} = -10V$	-80			A
Drain-Source On-State Resistance ¹	$R_{DS(\text{ON})}$	$V_{GS} = -10V, I_D = -24A$		5.5	6.8	$\text{m}\Omega$
		$V_{GS} = -4.5V, I_D = -15A$		8.5	11.5	
Forward Transconductance ¹	g_{fs}	$V_{DS} = -5V, I_D = -24A$		24		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = -15V, f = 1\text{MHz}$		4294		pF
Output Capacitance	C_{oss}			634		
Reverse Transfer Capacitance	C_{rss}			566		
Gate Resistance	R_g	$V_{GS} = 15\text{mV}, V_{DS} = 0V, f = 1\text{MHz}$		3.0		Ω
Total Gate Charge ^{1,2}	Q_g	$V_{DS} = -15V, V_{GS} = -10V, I_D = -25A$		62.4		nC
Gate-Source Charge ^{1,2}	Q_{gs}			8.5		
Gate-Drain Charge ^{1,2}	Q_{gd}			13		
Turn-On Delay Time ^{1,2}	$t_{d(\text{on})}$	$V_{DS} = -15V, I_D = -1A, V_{GS} = -10V, R_{GS} = 2.7\Omega$		18		nS
Rise Time ^{1,2}	t_r			26		
Turn-Off Delay Time ^{1,2}	$t_{d(\text{off})}$			22		
Fall Time ^{1,2}	t_f			75		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_C = 25^\circ\text{C}$)						
Continuous Current	I_S				-30	A
Pulsed Current ³	I_{SM}				-120	
Forward Voltage ¹	V_{SD}	$I_F = -24A, V_{GS} = 0V$			-1.2	V
Reverse Recovery Time	t_{rr}	$I_F = I_S, dI_F/dt = 100A / \mu\text{s}$		52		nS
Reverse Recovery Charge	Q_{rr}			60		nC

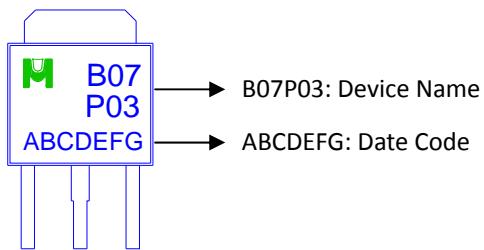
¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

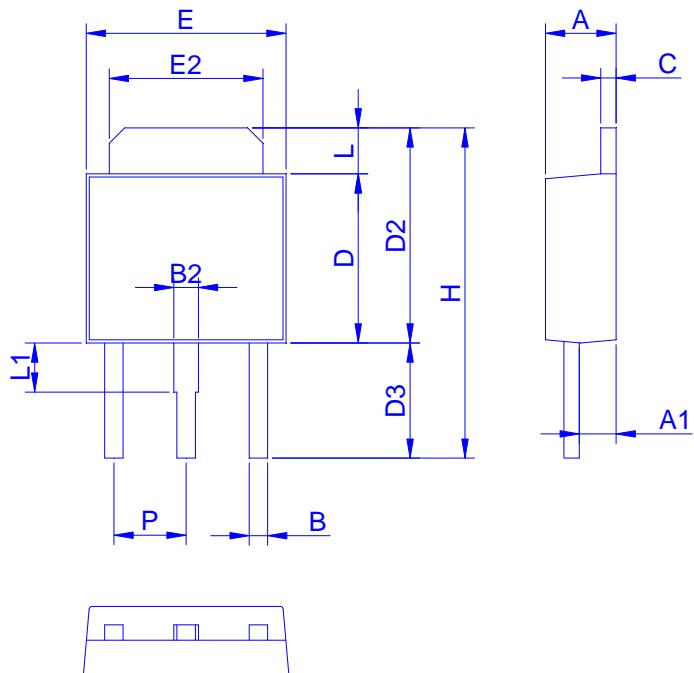
³Pulse width limited by maximum junction temperature.

Ordering & Marking Information:

Device Name: EMB07P03CS for IPAK (TO-251)



Outline Drawing



Dimension in mm

Dimension	A	A1	B	B2	C	D	D2	D3	E	E2	H	L	L1	P
Min.	2.10	0.90	0.40	0.60	0.40	5.30	6.70	3.40	6.30	4.80	10.2	0.89	0.90	2.10
Max.	2.50	1.50	0.90	1.15	0.60	6.25	7.30	4.30	6.80	5.50	11.5	1.40	1.80	2.50

